1,048,576 WORD × 4 BIT DYNAMIC RAM

This is advanced information and specifications are subject to change without notice.

DESCRIPTION

The TC514410AP/AJ/ASJ/AZ is the new generation dynamic RAM organized 1,048,576 words by 4 bits. The TC514410AP/AJ/ASJ/AZ utilizes TOSHIBA's CMOS Silicon gate process technology as well as advanced circuit techniques to provide wide operating margins, both internally and to the system user. Multiplexed address inputs permit the TC514410AP/AJ/ASJ/AZ to be packaged in a standard 20 pin plastic DIP, 26/20 pin plastic SOJ (300/350mil) and 20 pin plastic ZIP. The package size provides high system bit densities and is compatible with widely available automated testing and insertion equipment. System oriented features include single power supply of $5V\pm10\%$ tolerance, direct interfacing capability with high performace logic families such as Schottky TTL.

FEATURES

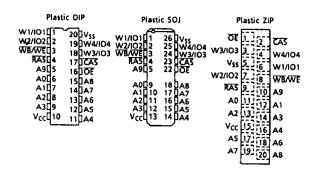
- 1,048,576 word by 4 bit organization
- Fast access time and cycle time

	TC514410AP/AJ/ASJ/ AZ - 60
t _{RAC} RAS Access Time	60ns
t _{AA} Column Address Access Time	30ns
t _{CAC} CAS Access Time	20ns
t _{RC} Cycle Time	110ns
t _{PC} Fast Page Mode Cycle Time	45ns

PIN NAMES

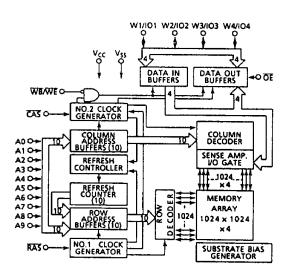
A0~A9	Address Inputs
RAS	Row Address Strobe
CAS	Column Address Strobe
WB/WE	Write Per Bit/Read/Write Input
ŌĒ	Output Enable
W1/I01~W4/I04	Write Select/Date Input/Output
V _{CC}	Power (+ 5V)
Vss	Ground

PIN CONNECTION (TOP VIEW)



- Single power supply of 5V $\pm 10\%$ with a built-in V_{BB} generator
- Low Power 660mW MAX. Operating (TC514410AP/AJ/ASJ/AZ-60) 5.5mW MAX. Standby
- Output unlatched at cycle end allows
- two-dimensional chip selection
 Read-Modify-Write, CAS before RAS
 refresh, RAS-only refresh, Hidden
 refresh, Write per Bit, Fast Page
 Mode and Test Mode capability
 All inputs and outputs TIL Compatible
- 1024 refresh cycles/16ms
 - Package TC514410AP TC514410AJ : DIP20-P-300C SOJ26-P-350 TC514410ASJ SOJ26-P-300A TC514410AZ : ZIP20-P-400A

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	RATING	UNITS	NOTES
Input Voltage	ViN	– 1∼7	٧	1
Output Voltage	Vout	- 1~7	٧	1
Power Supply Voltage	Vcc	- 1~7	v	1
Operating Temperature	TOPR	0~70	°C	1
Storage Temperature	T _{STG}	- 55~150	°C	1
Soldering Temperature · Time	TSOLDER	260 · 10	°C · sec	1
Power Dissipation	PD	700	mW	1
Short Circuit Output Current	lout	50	mA	1

RECOMMENDED DC OPERATING CONDITIONS ($Ta = 0 \sim 70$ °c)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT	NOTES
Vcc	Supply Voltage	4.5	5.0	5.5	٧	2
V _{tH}	Input High Voltage	2.4		6.5	V	2
VIL	Input Low Voitage	- 1.0	-	0.8	V	2

DC ELECTRICAL CHARACTERISTICS ($V_{CC} = 5V \pm 10\%$, $T_0 = 0 \sim 70$ °c)

SYMBOL	PARAMETER		MIN.	MAX.	UNITS	NOTES
l _{CC1}	OPERATING CURRENT Average Power Supply Operating Current (RAS, CAS, Address Cycling: t _{RC} =t _{RC} MIN.)	C514410AP/AJ/ASJ/AZ-60		120	mA	3, 4 5
lcc2	STANDBY CURRENT Power Supply Standby Current (RAS = CAS = V _{IH})			2	mA	
l _{CC3}	RAS ONLY REFRESH CURRENT Average Power Supply Current, RAS Only Mode (RAS Cycling, CAS = V _{IH} : t _{RC} = t _{RC} MIN.)	C514410AP/AJ/ASJ/AZ-60	-	120	mA	3, 5
I _{CC4}	FAST PAGE MODE CURRENT Average Power Supply Current, Fast Page Mode (RAS = V _{IL} , CAS, Address Cycling: t _{PC} = t _{PC} MIN.)	TC514410AP/AJ/ASJ/AZ-60	-	70	mA	3, 4 5
l _{CC} s	STANDBY CURRENT Power Supply Standby Current (RAS = CAS = V _{CC} - 0.2V)		<u>.</u>	1	mA	
lcc6	CAS BEFORE RAS REFRESH CURRENT Average Power Supply Current, CAS Before RAS Mode (RAS, CAS Cycling: t _{RC} =t _{RC} MIN.)	TC514410AP/AJ/ASJ/AZ-60	_	120	mA	3, 5
¹ ι (ι)	INPUT LEAKAGE CURRENT Input Leakage Current, any input (0V ≤ V _{IN} ≤ 6.5V, All Other Pins not under Test = 0V)		- 10	10	μА	
lo (L)	OUTPUT LEAKAGE CURRENT (D _{OUT} is disabled, $0V \le V_{OUT} \le 5.5V$)		- 10	10	μА	
V _{OH}	OUTPUT LEVEL Output "H" Level Voltage (I _{OUT} = -5mA)		2.4	-	V	
V _{OL}	OUTPUT LEVEL Output "L" Level Voltage (I _{OUT} = 4.2mA)		_	0.4	٧	

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS $(V_{CC} = 5V \pm 10\%, T_a = 0 \sim 70^{\circ}c)$ (Notes 6, 7, 8)

SYMBOL	0404445750	TC514410AP	AJ/ASJ/AZ-60		NOTES
STIVIBOL	PARAMETER	MIN.	MAX.	UNII	NOIES
t _{RC}	Random Read or Write Cycle Time	110	_	ns	
t _{RMW}	Read-Modify-Write Cycle Time	165		ns	
tpc	Fast Page Mode Cycle Time	45	-	ns	
t _{PRMW}	Fast Page Mode Read-Modify-Write Cycle Time	100		ns	
t _{RAC}	Access Time from RAS	-	60	ns	9,14 15
t _{CAC}	Access Time from CAS	-	20	ns	9,14
t _{AA}	Access Time from Column Address	-	30	ns	9,15
t _{CPA}	Access Time from CAS Precharge		40	ns	9
t _{CLZ}	CAS to output in Low-Z	0	-	ns	9
t _{OFF}	Output Buffer Turn-off Delay	0	20	ns	10
t _T	Transition Time (Rise and Fall)	3	50	ns	8
t _{RP}	RAS Precharge Time	40	-	ns	
t _{RAS}	RAS Pulse Width	60	10,000	ns	
t _{RASP}	RAS Pulse Width (Fast Page Mode)	60	200,000	ns	
t _{RSH}	RAS Hold Time	20	-	ns	
t _{RHCP}	RAS Hold Time From CAS Precharge (Fast Page Mode)	40	_	ns	
t _{CSH}	CAS Hold Time	60		ns	
t _{CAS}	CAS Pulse Width	20	10,000	ns	
t _{RCD}	RAS to CAS Delay Time	20	40	ns	14
t _{RAD}	RAS to Column Address Delay Time	15	30	ns	15
t _{CRP}	CAS to RAS Precharge Time	5	-	ns	
t _{CP}	CAS Precharge Time	10	_	ns	
t _{ASR}	Row Address Set-Up Time	0	-	ns	
t _{RAH}	Row Address Hold Time	10	_	ns	
tasc	Column Address Set-Up Time	0	-	ns	
t _{CAH}	Column Address Hold Time	15	_	ns	
tRAL	Column Address to RAS Lead Time	30	_	ns	
t _{RCS}	Read Command Set-Up Time	0	_	ns	
t _{RCH}	Read Command Hold Time	0		ns	11

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

		TC514410AP/AJ/ASJ/AZ-60	/AJ/ASJ/AZ-60		NOTES
SYMBOL	PARAMETER	MIN.	MAX.	UNITS	
terh	Read Command Hold Time referenced to RAS	0	_	ns	11
twch	Write Command Hold Time	10	4	ns	
twp	Write Command Pulse Width	10	-	ns	
t _{RWL}	Write Command to RAS Lead Time	20	-	ns	
t _{CWL}	Write Command to CAS Lead Time	20	-	ns	
tos	Data Set-Up Time	0	-	ns	12
[₹] DH	Data Hold Time	15	-	ns	12
t _{REF}	Refresh Period		16	ms	
twcs	Write Command Set-UP Time	0	-	ns	13
tcwp	CAS to WE Delay Time	50	-	ns	13
t _{RWD}	RAS to WE Delay Time	90	-	ns	13
tawo	Column Address to WE Delay Time	60	-	ns	13
tcpwD	CAS Precharge to WRITE Delay Time	70	-	ns	13
t _{CSR}	CAS Set-Up Time (CAS before RAS Cycle)	5	-	ns	
t _{CHR}	CAS Hold Time (CAS before RAS Cycle)	15	-	ns	
t _{RPC}	RAS to CAS Precharge Time	0	_	ns	
t _{CPT}	CAS Precharge Time (CAS before RAS Counter Test Cycle)	30	-	ns	
t _{ROH}	RAS Hold Time referenced to OE	10	-	ns	
t _{OEA}	OE Access Time		20	ns	
toto	ŌĒ to Data Delay	20	_	ns	
t _{OE2}	Output buffer turn off Delay Time from $\overline{\text{OE}}$	0	20	ns	
t _{OEH}	OE Command Hold Time	20	-	ns	
twas	Write Per Bit Set-Up Time	0	_	ns	
t _{WBH}	Write Per Bit Hold Time	10	_	ns	
twos	Write Per Bit Selection Set-Up Time	0	-	ns	
twoH	Write Per Bit Selection Hold Time	10	-	ns	



ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

SYMBOL	PARAMETER	TC514410AP	TC514410AP/AJ/ASJ/AZ-60		
		MIN.	MAX.	UNIT	NOTES
twrs	Write Command Set-up Time	10	_	ns	
twtH	Write Command Hold Width	10	-	ns	
twRP	WE to RAS Precharge Time	10	-	ns	
twee	WE to RAS Hold Time	10	-	ns	

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS IN THE TEST MODE ($V_{CC} = 5V \pm 10\%$, $T_{a} = 0 \sim 70^{\circ}c$) (Notes 6, 7, 8)

SYMBOL	PARAMETER	TC514410AP/A	TC514410AP/AJ/ASJ/AZ-60		
		MIN.	MAX.	TINU	NOTES
t _{RC}	Random Read or Write Cycle Time	115	-	ns	
tpC	Fast Page Mode Cycle Time	50		ns	
t _{RAC}	Access Time from RAS	-	65	ns	9,14, 15
t _{CAC}	Access Time from CAS	_	25	ns	9,14
taa	Access Time from Column Address	-	35	ns	9,15
t _{CPA}	Access Time from CAS Precharge	-	45	ns	9
t _{RAS}	RAS Pulse Width	65	10,000	ns	
t _{RASP}	RAS Pulse Width (Fast Page Mode)	65	200,000	ns	
t _{RSH}	RAS Hold Time	25	-	ns	
t _{CSH}	CAS Hold Time	65	-	ns	
t _{RHCP}	CAS Precharge to RAS Hold Time	45	_	ns	
t _{CAS}	CAS Pulse Width	25	10,000	ns	
LRAL	Column Address to RAS Lead Time	35	-	ns	

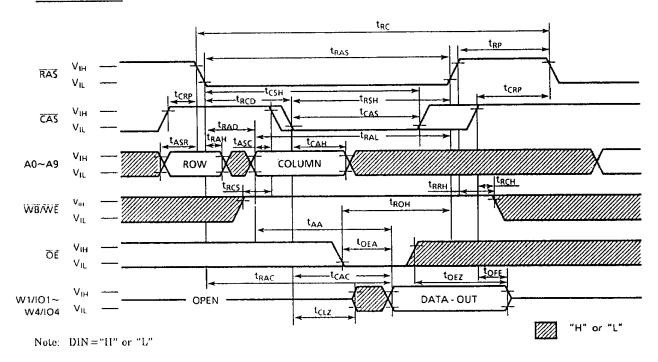
CAPACITANCE ($V_{CC} = 5V \pm 10\%$, f = 1MHz, $Ta = 0 \sim 70$ °c)

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
C ₁₁	Input Capacitance (A0~A9)	-	5	рF
C ₁₂	Input Capacitance (RAS, CAS, WB/WE, OE)	-	7	рғ
co	Input/Output Capacitance (W1/IO1~W4/IO4)	-	7	pF

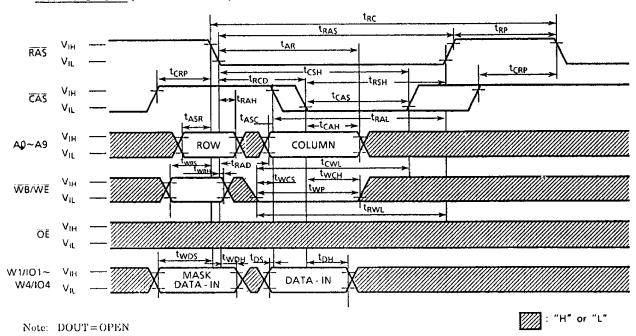
NOTES:

- 1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.
- 2. All voltages are referenced to VSS.
- 3. ICC1, ICC3, ICC4, ICC6 depend on cycle rate.
- 4. ICC1, ICC4 depend on output loading. Specified values are obtained with the output open.
- 5. Column address can be changed once or less while $\overline{RAS} = V_{IL}$ and $\overline{CAS} = V_{IH}$.
- 6. An initial pause of 200µs is required after power-up followed by 8 RAS only refresh before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 CAS before RAS refresh cycles instead of 8 RAS refresh cycles are required.
- 7. AC measurements assume $t_T=5$ ns.
- 8. V_{III} (min.) and V_{IL} (max.) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{III} and V_{IL} .
- 9. Measured with a load equivalent to 2 TTL loads and 100pF.
- 10. topp (max.) and defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
- 11. Either tRCH or tRRH must be satisfied for a read cycle.
- 12. These parameters are referenced to CAS leading edge in early write cycles and to WRITE leading edge in Read-Write cycles.
- 13. twcs, trwd, tcwd, tawd and tcpwd are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If twcs≥twcs (min.), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; If trwd≥trwd (min.), tcwd≥tcwd (min.), tawd≥tawd (min.) and tcpwd≥tcpwd (min.) (Fast Page Mode), the cycle is a Read-Write cycle and the data out will contain data read from the selected cell: If neither of the above sets of conditions is satisfied, the condition of the data out (at aecess time) is indeterminate.
- 14. Operation within the t_{RCD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RCD} (max.) is specified as a reference point only: If t_{RCD} is greater than the specified t_{RCD} (max.) limit, then access time is controlled by t_{CAC}.
- 15. Operation within the t_{RAD} (max.) limit insures that t_{RAC} (max.) can be met.
 t_{RAD} (max.) is specified as a reference point only: If t_{RAD} is greater than the specified t_{RAD} (max.) limit, then access time is controlled by t_{AA}.

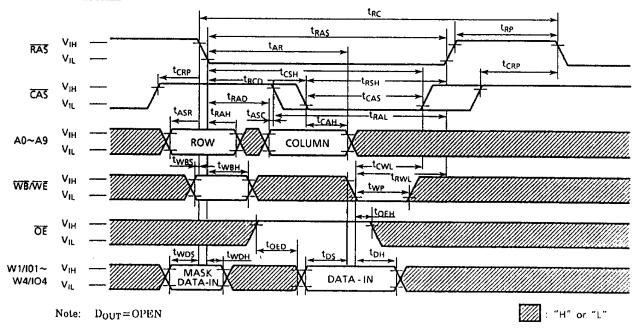
READ CYCLE



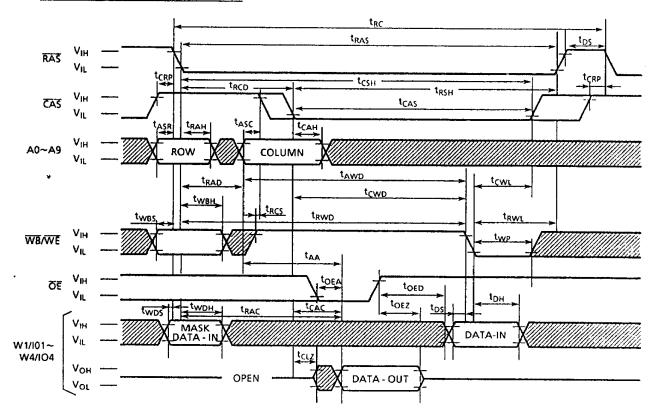
WRITE CYCLE (EARLY WRITE)



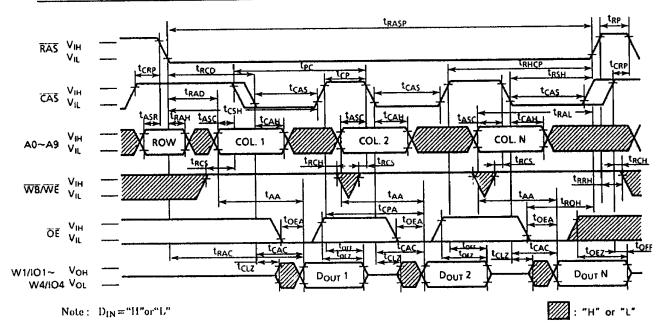
WRITE CYCLE (OE CONTROLLED WRITE)



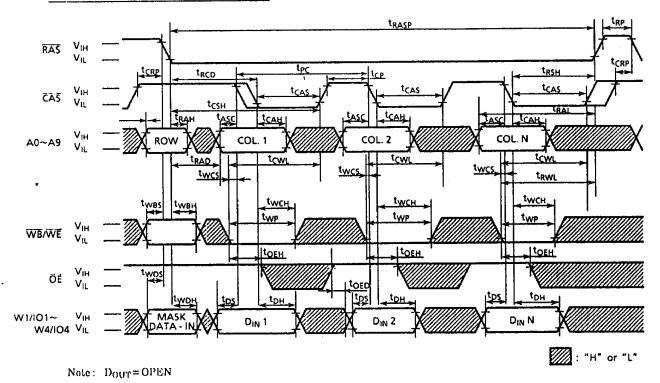
READ - MODIFY - WRITE CYCLE



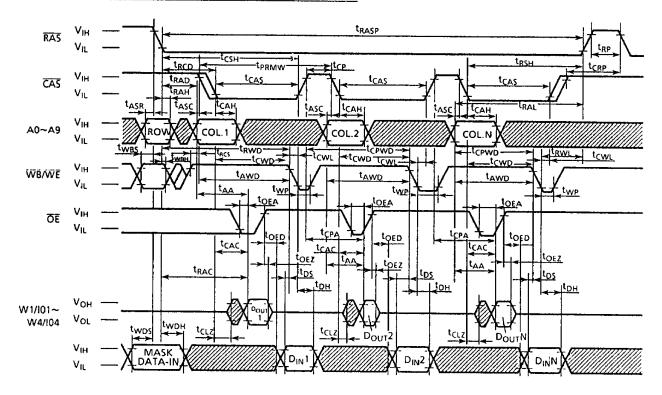
FAST PAGE MODE READ CYCLE



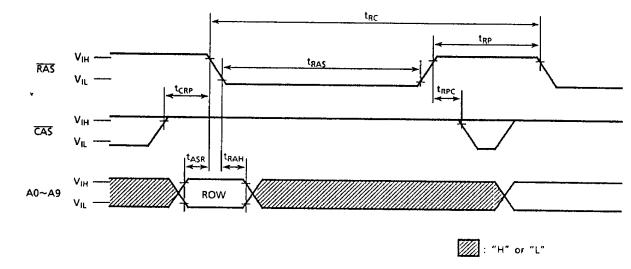
FAST PAGE MODE WRITE CYCLE



FAST PAGE MODE READ-MODIFY-WRITE CYCLE

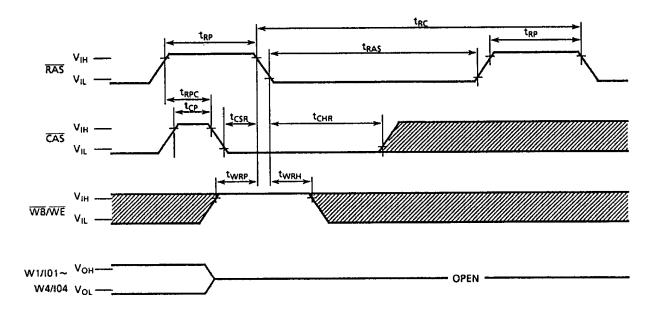


RAS ONLY REFRESH CYCLE



Note: WRITE, OE = "H" or "L"

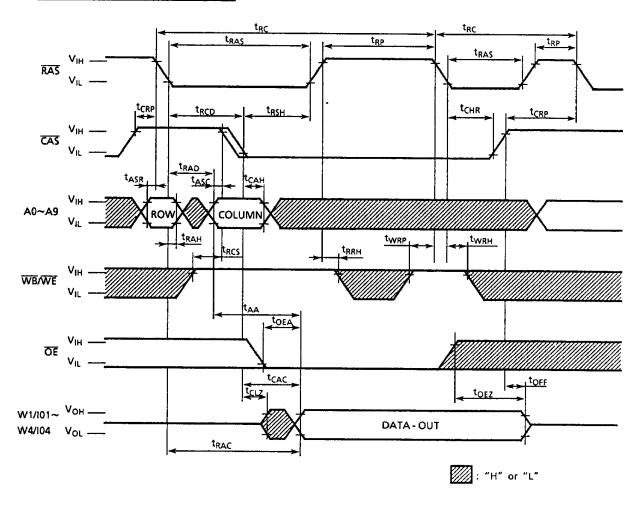
CAS BEFORE RAS REFRESH CYCLE



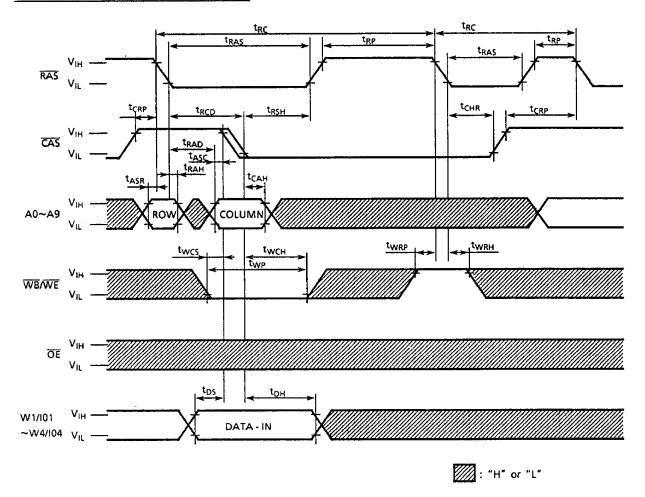
Note: D_{IN} , \overrightarrow{OE} , $A0\sim A9 = "H"$ or "L"

: "H" or "L"

HIDDEN REFRESH CYCLE (READ)

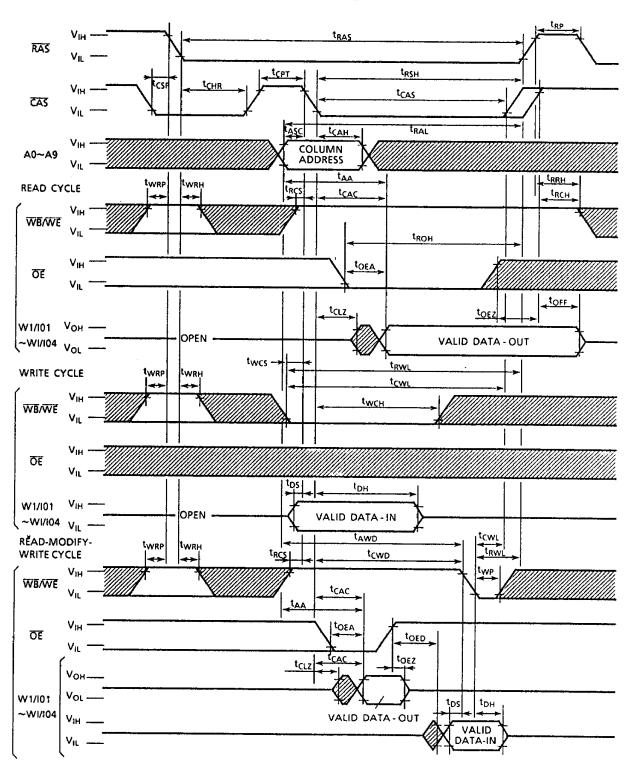


HIDDEN REEFRESH CYCLE (WRITE)

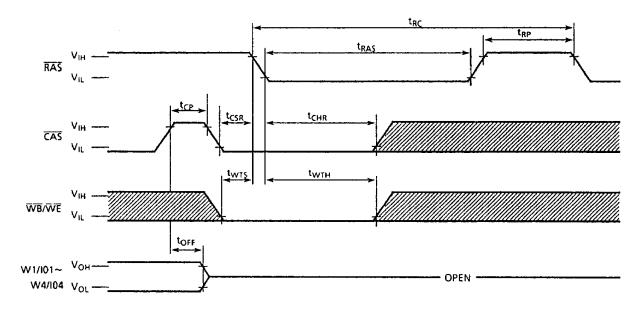


A-501

CAS BEFORE RAS REFRESH COUNTER TEST CYCLE



WE, CAS BEFORE RAS REFRESH CYCLE



Note: D_{1N} , \overline{OE} , $A0\sim A9 = "H"$ or "L"

: "H" or "L"

APPLICATION INFORMATION

ADDRESSING

The 20 address bits required to decode 1 of the 1,048,576 cell locations within the TC51410AP/AJ/ASJ/AZ are multiplexed onto the 10 address inputs and latched into the on-chip address latches by externally applying two negative going TTL-level clocks.

The first clock, the Row Address Strobe (\overline{RAS}), latches the 10 row address bits into the chip. The second clock, the Column Address Strobe (\overline{CAS}), subsequently latches the 10 column address bits into the chip. Each of these signals, \overline{RAS} , and \overline{CAS} , triggers a sequence of events which are controlled by different delayed internal clocks.

The two clock chains are linked together logically in such a way that the address multiplexing operation is done outside of the critical path timing sequence for read data access. The later events in the \overline{CAS} clock sequence are inhibited until the occurrence of a delayed signal derived from the \overline{RAS} clock chain. The "gated \overline{CAS} " feature allows the \overline{CAS} clock to be externally activated as soon as the Row Address Hold Time specification (t_{RAII}) has been satisfied and the address inputs have been changed from Row address to Column address information.

DATA INPUTS

A write cycle is performed by bringing $(\overline{WB}/)$ \overline{WE} low during the $\overline{RAS}/\overline{CAS}$ operation. The falling edge of \overline{CAS} or $(\overline{WB}/)$ \overline{WE} strobes data on (Wi) IOi into the on-chip data latch. To make use of the write-per-bit capability $\overline{WB}(/\overline{WE})$ must be low as \overline{RAS} falls. In this case data bits to which the write operation is applied can be specified by keeping Wi (/IOi) high with set-up and hold times referenced to the \overline{RAS} negative transition. For those data bits of Wi (/IOi) that are kept low as \overline{RAS} talls the write operation is inhibited on the chip if $\overline{WB}(/\overline{WE})$ is high as \overline{RAS} falls, the write-per-bit capability does not work and the write operation is performed for all four data bits.

DATA OUTPUTS

The three-state output buffers provide direct TTL compatibility with a fan-out of two standard TTL loads. Data-out is the same polarity as data-in. The outputs are in the high-impedance state until $\overline{\text{CAS}}$ is brought low. In a read cycle the outputs go active after the access time interval t_{RAC} and t_{OEA} are satisfied.

The outputs become valied after the access time has elapsed and remains valied while \overline{CAS} and \overline{OE} are low. \overline{CAS} or \overline{OE} going high returns it to a high impedance state. In an early-write cycle, the outputs are always in the high-impedance state. In a delayed-write or read-modify-write cycle, the outputs will follow the sequence for the read cycle.

The \overline{OE} controls the impedance of the output buffers. In the logic high position the buffers will remain in a high impedance state.

When the \overline{OE} input is brought to a logical low level, the output buffer are enabled. Both \overline{CAS} and \overline{OE} can control the output. Thus in a read operation, either \overline{OE} or \overline{CAS} returning high forces the outputs into the high impedance state.

RAS ONLY REFRESH

Refresh of the dynamic cell matrix is accomplished by performing a memory cycle at each of the 512 row address (A0~A9) within each 16 millisecond time interval.

Although any normal memory cycle will perform the refresh operation, this function is most easily accomplished with "RAS-only" cycles.

CAS BEFORE RAS REFRESH

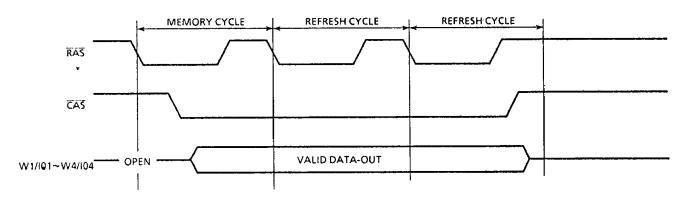
 $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refreshing available on the TC514410AP/AJ/ASJ/AZ offers an alternate refresh method. If $\overline{\text{CAS}}$ is held on low for the specified period (tCSR) before $\overline{\text{RAS}}$ goes to low, on chip refresh control clock generators and the refresh address counter are enabled, and an internal refresh operation takes place. After the refresh operation is performed, the refresh address counter is automatically incremented in preparation for the next $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh operation.

PAGE MODE

The "Page-Mode" feature of the TC514410AP/AJ/ASJ/AZ allows for successive memory operations at multiple column locations of the same row address with increased speed without an increase in power. This is done by strobing the row address into the chip and maintaining the RAS signal at a logic 0 throughout all successive memory cycles in which the row address is common. This "Page-Mode" of operation will not dissipate the power associated with the negative going edge of RAS. Also, the time required for strobing in a new address is eliminated, thereby decreasing the access and cycle times.

HIDDEN REFRESH

An optional feature of the TC514410AP/AJ/ASJ/AZ is that refresh cycles may be performed while maintaining valid data at the output pin. This is referred to as Hidden Refresh. Hidden Refresh is performed by holding \overline{CAS} at V_{IL} and taking \overline{RAS} high and after a specified precharge period (t_{RP}), executing a \overline{CAS} before \overline{RAS} refresh cycle. (see Figure below)



This feature allows a refresh cycle to be "Hidden" among data cycles without affecting the data availability.



CAS BEFORE RAS REFRESH COUNTER TEST

The internal refresh operation of TC514410AP/AJ/ASJ/AZ can be tested by CAS BEFORE RAS REFRESH COUNTER TEST. This cycle performs READ/WRITE operation taking the internal counter address as row address and the input address as column address.

The test is performed after a minimum of 8 CAS before RAS cycles as initialization cycles. The test procedure is as follows.

- ① Write "0" into all the memory cells at normal write mode.
- ② Select one certain column address and read "0" out and write "1" in each cell by performing CAS BEFORE RAS REFRESH COUNTER TEST (READ-WRITE CYCLE). Repeat this operation 512 times.
- 3 Check "1" out of 512 bits at normal read mode, which was written at 2.
- Wing the same column as ②, read "1" out and write "0" in each cell performing CAS BEFORE RAS REFRESH COUNTER TEST. Repeat this operation 512 times.
- S Check "0" out of 512 bits at normal read mode, which was written at 4.
- 6 Perform the above 1 to 5 to the complement data.

TEST MODE

The TC514410AP/AJ/ASJ/AZ is the RAM organized 1,048,576 words by 4 bits, it is internally organized 524,288 words by 8 bits. In "Test Mode", data are written into 8 sectors in parallel and retrieved the same way. A₀₀ is not used. If, upon reading, two bits on one I/O pin are equal (all "1"s or "0"s), the I/O pin indicates a "1". If they were not equal, the I/O pin would indicate a "0". Fig. 1 shows the block diagram of TC514410J/Z. In "Test Mode", the 1M×4 DRAM can be tested as if it were a 512K×4 DRAM.

"WE, CAS Before RAS Refresh Cycle" puts the device into "Test Mode". And "CAS Before RAS Refresh Cycle" or "RAS Only Refresh Cycle" puts it back into "Normal Mode". In the Test Mode, "WE, CAS Before RAS Refresh Cycle" performs the refresh operation with the internal refresh address counter. The "Test Mode" function reduces test times (1/2 in case of N test pattern).

BLOCK DIAGRAM IN THE TEST MODE

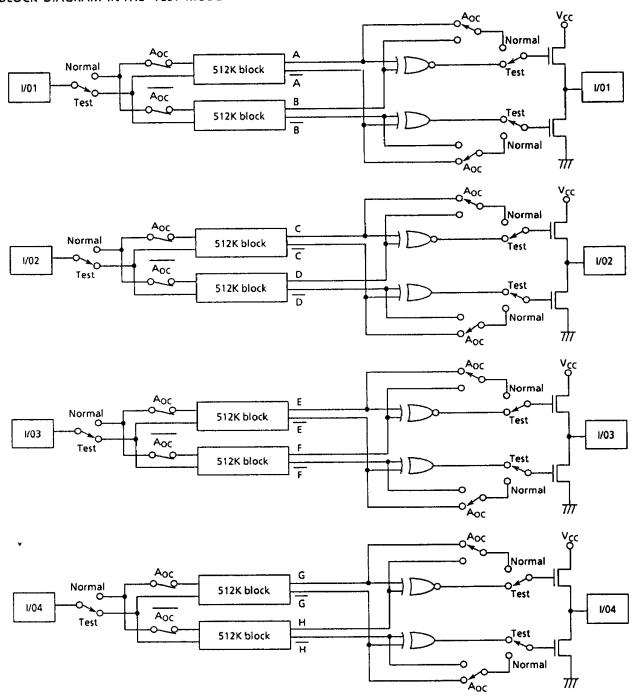


Fig. 1